

ALPHA OM-350 NO-CLEAN LEAD-FREE SOLDER PASTE

DESCRIPTION

ALPHA OM-350 is a lead-free, no-clean solder paste suitable for fine feature printing and reflow using most demanding soak reflow profiles in air and nitrogen atmospheres.

The outstanding reflow process window of **ALPHA OM-350** delivers good soldering on OSP-Cu, Immersion Ag, Immersion Sn, ENIG and Lead-Free HASL surface finishes.

ALPHA OM-350's compliance with ROL0 IPC and IPC Class III voiding classifications ensures maximum long-term product reliability.

Compliance to environmental standards, including RoHS allows global application of **ALPHA OM-350**.

FEATURES & BENEFITS

- **Excellent Pin-in-Paste (Paste-in-Hole) Performance:** demonstrated both for printing, dispensing (or pin transfer) SMT applications.
- **Long Stencil Life:** consistent performance for at least 6 hours of continuous printing without addition of new paste. 24 hour SMT production ability achieved from 20°C up to 32°C (68°F - 90°F) harsh environments.
- **Stable Paste Viscosity:** allows wide storage and handling window at temperatures up to 30°C for 21 days, and up to 25°C for one month.
- **High Tack Force:** ensures high pick-and-place yields, good self-alignment and a low tomb-stoning defect rate.
- **Wide Reflow Profile Window:** allows best quality solderability of complicated, high-density PWB assemblies in both air and nitrogen reflow, using straight ramp or soak profiles up to 200°C.
- **Robust Solderability:** proven to handle difficult wetting requirements of critical lead-free components, such as CSP and QFN...etc. on a variety of lead-free board finishes, OSP-Cu, Immersion Ag, Immersion Sn, ENIG & LF HASL.
- **Reduced Random Solder Ball Levels:** minimizes rework and increases first time yield.
- **Voiding Performance:** meets highest IPC classification of Class III for important ball grid array components.
- **Excellent Solder Joint and Flux Residue Cosmetics:** after reflow soldering even using long/high thermal soaking without charring or burning.
- **First-rate Reliability Properties:** excess variety of industry and customer standards, halide free material graded ROL0 according to IPC classification.
- **Safe and Environmentally Friendly:** materials comply with RoHS requirement, as well as TOSCA & EINECS. No toxic material used in the paste.

The information contained herein is based on data considered accurate and is offered at no charge. No warranty is expressed or implied regarding the accuracy of this data. Liability is expressly disclaimed for any loss or injury arising out of the use of this information or the use of any materials designated.

12/6/07





PHYSICAL PROPERTIES

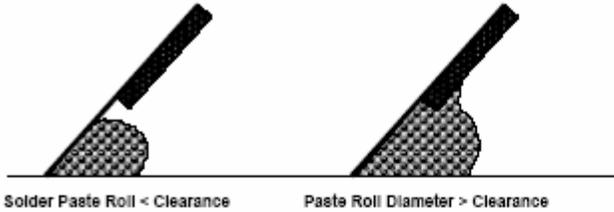
- Alloys:** **SAC305** (96.5%Sn 3.0%Ag 0.5%Cu)
 SACX 0307 (99% Sn 0.3% Ag 0.7% Cu)
 Also available in other Sn-Ag-Cu alloys upon request
- Powder Size:** **Type 3** (25 - 45 μ m per IPC J-STD-005)
Type 4 (20 - 38 μ m per IPC J-STD-005)
Type 5 (<25 μ m per IPC J-STD-005)
- Residue:** Approximately 5% by weight
- Packaging Sizes:** **500 gram jars** (standard package), 500/1000g cartridges also available.

RECOMMENDED APPLICATION SETTINGS

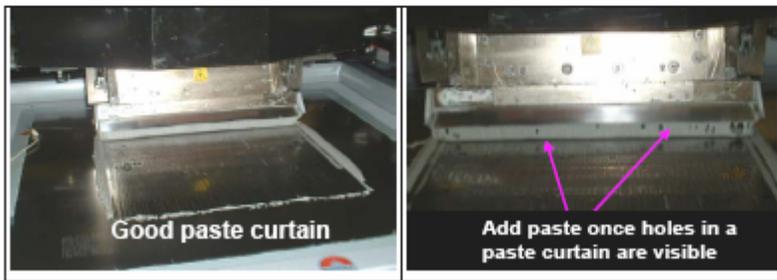
The following are the general guidelines for initial SMT process set-up using well maintained equipment and properly handled materials. Some deviations from the guidelines may occur for specific combinations of PWB assemblies and SMT equipment.

A. PRINTING

Parameter	Guideline	Additional Information
Stencil Design	Pad/wall area ratio >0.55 to achieve consistently good paste deposits. Laser cut or Electroform stencils.	References minimum circle sizes for various stencil thickness: 330 μ m (~13 mil) circle w/ 0.15mm (6 mil) stencil 280 μ m (~11 mil) circle w/ 0.12mm (5 mil) stencil 225 μ m (9 mil) circle w / 0.10mm (4 mil) stencil
Squeegee	Metal squeegee	
Down Stop (MPM printer only)	1.9 to 2.2 mm (0.07 – 0.09 in.)	MPM specific setting.
Printing Pressure	0.15 – 0.40kg/cm (0.84 – 2.2 lb/in)	Pressure to be optimized for specific assembly
Printing Speed	25 - 100 mm/second (1 – 4 in/second)	50 mm/second - 2 in/ second preferred
Separation Speed	1 - 20 mm/second (0.04 – 0.8 in/second)	Slow release is recommended (separation speed should be set up under microscope inspection of deposit)
Squeegee Lift & Dwell Height	10 - 15 mm (0.4 – 0.6 in) recommended	Please refer to the details below
Working Temperature	20°C – 32 °C (68°F – 90°F)	
Paste Volume to Add	Paste volume should be kept just below the squeegee assembly clearance	Minimize paste sticking to the squeegee holder which increases maintenance and degrades the paste



Certain squeegee designs require that the maximum amount of paste is limited to avoid “stick to squeegee” phenomenon.



Paste should be added when incomplete paste curtain is formed between squeegee and stencil using 10 to 15 mm squeegee dwell/lifting height.

B. REFLOW

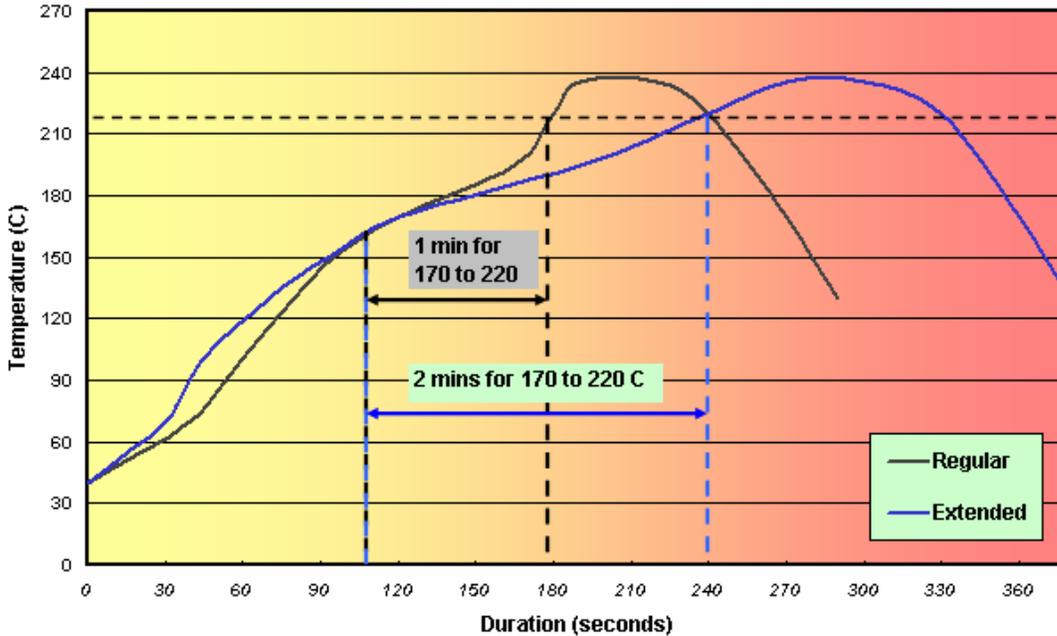
Parameter	Guideline	Additional Information
Atmosphere	Air or N ₂	Laboratory paste performance is typically verified in air. Successful production verification both in air and N ₂ .
SnAgCu alloy melting points	SAC305: 217 – 220 °C SAC405: 217 – 225 °C SAC387: 217 – 220°C SAC359/396: 217°C SACX 0307: 217-227°C Innot: 108 - 214°C Sn 95/ Sb 5: 240-243 °C	Use for reflow above liquidus setting
Profile General Guideline (Typical for SAC305)		
Setting Zone	Dwell Period	Extended Window (provided that there is no concern of component & PWB damage)
40°C to 220°C	<4 min	< 4 min.
130°C to 220°C	<2 min. 30 sec.	< 3 min.
170°C to 220°C	<1 min. 30 sec.	< 2 min.
Above 220°C	45 - 90 sec.	
Peak temp.	< 240°C for standard OSP finish. 240-250 °C for Entek® HT OSP finish.	240 - 250 °C max. for other surface finishes (ENIG, Immersion Ag or Immersion Sn, LF, HASL...etc.)
Joint cool down rate from 170□	> 3°C – 8°C	Recommended to prevent surface cracking issues



Reflow Profile of Alpha OM-350 L-F Solder Paste

95.5Sn/3Ag/0.5Cu (M.P. 217 to 220 range) SAC305 Alloy

alpha



C. CLEANING

Parameter	Guideline	Additional Information
Stencil & Misprint Cleaning	<ul style="list-style-type: none"> → IPA → Bioact SC-10, Bioact SC-10E, Bioact SC-10E Plus, Bioact EC7-MT1 → ALPHA SM-110, ALPHA SM-110E 	Available from Alpha
Removing Reflow Residues	<ul style="list-style-type: none"> → Hydrex LF (Petroferm) → ALPHA BC-2400 and BC-2200 → Aquanox A4520 and A4630 (Kyzen) → WS2104/2107/WS1942/WS1863 (Kaken Solvent) 	Aqueous Cleaning
	<ul style="list-style-type: none"> → Bioact EC7-M → ALPHA BC-3300 	Ultrasonic Semi-aqueous Cleaning
	<ul style="list-style-type: none"> → Bioact SC-10, Bioact SC-10E, Bioact SC-10E Plus → ALPHA SM-110, ALPHA SM-110E 	Manual

→ Please consult with Alpha Technical support for detail application conditions for cleaning.

RELIABILITY DATA AND PHYSICAL PROPERTIES

CATEGORY	RESULTS	PROCEDURES/REMARKS
CHEMICAL PROPERTIES		
Activity Level	ROL-0 = J-STD Classification	IPC J-STD-004

The information contained herein is based on data considered accurate and is offered at no charge. No warranty is expressed or implied regarding the accuracy of this data. Liability is expressly disclaimed for any loss or injury arising out of the use of this information or the use of any materials designated.



Halide Content	Halide free (by titration & IC)	IPC J-STD-004
Ag Chromate Test	PASS	IPC J-STD-004
Copper Mirror Test	PASS	IPC J-STD-004
Copper Corrosion Test	PASS	IPC J-STD-004
	PASS	JIS Z 3197-1986
Talc Test	PASS	JIS Z 3197
ELECTRICAL PROPERTIES		
IPC SIR (168 hours @ 85° C/85% RH)	PASS, 1.8×10^{10} ohms	IPC J-STD-004 {Pass $\geq 1 \times 10^8$ ohm min}
Bellcore SIR (96 hours @ 35°C/85%RH)	PASS, 1.9×10^{12} ohms	Bellcore GR78-CORE {Pass $\geq 1 \times 10^{11}$ ohm min}
IPC/Bellcore Electromigration (Bellcore 96 hours @ 65°C/85%RH 10V 500 hours)	PASS, Initial = 7.8×10^8 ohms Final = 8.2×10^9 ohms	Bellcore GR78-CORE {Pass = final > initial/10}
JIS Electromigration (1000 hours @ 85°C/85%RH 48V 1000 hours)	Final Reading > 1.0×10^{10} ohms No migration after 1000 hrs PASS	JIS-Z-3197-1999
HP ECM Test (28 days @ 50°C/90%RH 5V)	PASS on Cu/ImmAg/ImmSn finish No migration after 28 days	Hewlett-Packard EL-EN861-00 {Pass $\geq 1 \times 10^8$ ohm min}
PHYSICAL PROPERTIES		
Color	Clear, Colorless Flux Residue	
Tack Force vs. Humidity (t=8 hours)	Pass , <10% change Over 100 gf after 24 hours when stored at 25±2°C and 50±10% R.H.	JIS Z3284 Annex 9
Viscosity	88.8% metal designated M16 for Type 5 89.0% metal designated M16 for Type 4	Malcom Spiral Viscometer; JIS Z3284 Annex 6
Solder Ball	Acceptable (SAC 305 alloy) Tested after 4 hours storage @ 25%, 50% and 85% RH.	IPC TM-650 2.4.43/JIS Z3284 Annex 11
Stencil Life	> 6 hours	25°C (77°F)
Spread	> 80 %	JIS-Z-3197: 1999 8.3.1.1
Hot Slump	PASS	IPC J-STD-005 (10 min 150°C)
	PASS No bridge for 0.2mm space	JIS-Z-3284-1994 Annex 8

SAFETY

While the **ALPHA OM-350** flux system is not considered toxic, its use in typical reflow will generate a small amount of reaction and decomposition vapors. These vapors should be adequately exhausted from the work area. Consult the MSDS for complete safety information.



STORAGE & HANDLING

<i>Condition</i>	<i>Period</i>
Refrigeration @ 0-10°C (32-50°F)	6 months
Room temperature (25°C)	1 month
30°C	3 weeks

- When refrigerated, warm-up the sealed paste container to room temperature for up to 4 hours in order to prevent moisture penetration into the paste.
- Printing can be performed at temperatures up to 32°C (90°F).
- Do not remove worked paste from stencil and mix with unused paste in jar. This will alter the rheology of unused paste.
- These are starting recommendations and all process settings should be reviewed independently.